



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|-----------------|
| Case Code | 40 |
| L | 7.9mm +/-0.38mm |
| W | 12.2mm +/-0.4mm |
| H | 8.9mm +/-0.38mm |
| S | 1.4mm +/-0.38mm |
| F | 10.5mm +/-0.4mm |
| K | 6.6mm +/-0.38mm |

Packaging Specifications

Packaging T&R, 178mm

General Information

| | |
|---------------------|--|
| Series | TSP |
| Dielectric | Polymer Tantalum |
| Style | Stacked Chip |
| Description | SMD, Polymer, KO, Stacks, High Reliability |
| Features | High Reliability |
| RoHS | Yes |
| Termination | Tin |
| Termination (Stack) | Solder Coated |
| AEC-Q200 | No |

Specifications

| | |
|-------------------------|--|
| Capacitance | 4,000 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 6.3 VDC (105C), 4.22 VDC (125C) |
| Temperature Range | -55/+125°C |
| Rated Temperature | 105°C |
| Dissipation Factor | 10% 120Hz 25C |
| Failure Rate | D (0.001%/1000 Hrs) |
| Resistance | 5 mOhms (100kHz 25C) |
| Leakage Current | 2520 uA (5min 25°C) |
| Testing and Reliability | 10 Cycles Surge Current Testing At -55C And +85C |